161 (h01021s, ipc, 232015s, ipc, 2301 (clectrode cathode anode) with (curve curves curve) and ((ceramica lumina dielectric insulating insulatine insulating) insulatine insulating insulatine insulating insulatine insulating insulatine insulating insulation with (curve curves curvature curving nonplanar concave convex))   2538 (165/345.47; 165/345.45; 155/345.45; 156/345.45; 156/345.47; 165/345.47; 165/345.45; 156/345.46; 156/345.47; 165/345.47; 156/345.46; 156/345.47;					
and ((ceramic alumina dielectric insulate insulating insulates insulating insulates insulating in insulates insulating in forplanes concave convex)  158/345-43; 156/345-44; 156/345-46; 156/345-46; 156/345-43; 156/345-43; 156/345-44; 156/345-46; 156/345-43; 156/345-44; 156/345-45; 156/345-46; 156/345-47, CCLS.) ((118/723e)-CCLS.)  48 (((156/345-43); 156/345-44; 156/345-45; 156/345-46; 156/345-47), CCLS.) ((118/723e)-CCLS.) (1018/723e)-CCLS.) (1018	-	161		JPO;	2003/06/28 23:05
insulates insulation) with (curve curves curvature curving nonplanar concave convex))  538 (156/345.43; 156/345.44; 156/345.45; 156/345.46; USPAT 2004/01/13 08:05 156/345.47),CCLS.  978 (118/723e),CCLS. 1292 (1156/345.43; 156/345.44; 156/345.45; 156/345.46; USPAT 2004/01/13 08:07 156/345.47),CCLS.) (118/723e),CCLS.)				DERWENT	
nonplanar concave convexy) 158 (156/345.47);CGLS. 158/345.47);CGLS. 158/345.47);CGLS. 11829 (118/723e);CGLS. 1292 (118/732e);CGLS. 1293 (118/732e);CGLS. 1294 (118/732e);CGLS. 1294 (118/732e);CGLS.) 1295 (118/732e);CGLS.) 1296 (118/732e);CGLS.) 1299 (118/732e);CGLS.) 12994 (118/73e);CGLS.) 12995 (118/73e);CGLS.) 12995 (118/73e);CGLS.) 12996 (118/73e);CGLS.) 12996 (118/73e);CGLS.) 12996 (118/73e);CGLS.) 12996 (118/73e);CGLS.) 12996 (118/73e);CGLS.) 12997 (118/73e);CGLS.) 12997 (118/73e);CGLS.) 12997 (118/73e);CGLS.) 12997 (118/73e);CGLS.) 12997 (118/73e);CGLS.) 12997 (118/73e);CGLS.) 12998 (118/73e);CGLS.) 12998 (118/73e);CGLS.) 12998 (118/73e);CGLS.) 12999 (11		:			
538 (156/345.43; 156/345.44; 156/345.46; 156/345.46; 156/345.47).CCLS.   158/345.47).CCLS.   118/723e).CCLS.   118/723e).CCLS.   118/723e).CCLS.   118/723e).CCLS.   118/723e).CCLS.   118/7345.47].CCLS.   118/723e).CCLS.   118/723e].CCLS.   118					
156/345.43/1.CCLS.   159/345.44; 156/345.45; 156/345.46; USPAT   2004/01/13 08:07   156/345.47).CCLS.   ((1156/345.43; 156/345.44; 156/345.45; 156/345.46; USPAT   2004/01/13 08:07   156/345.47).CCLS.   ((1156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.   ((1156/345.43; 156/345.45; 156/345.45; 156/345.46; 156/345.47).CCLS.   ((1167/232)).CRLS.   USPAT   2004/01/13 09:07   (1570/25627).PN.   USPAT   2004/01/13 09:07   (1570/25627).PN.   USPAT   2004/01/13 10:00   (156/345.43.45.)   (156/345.43.45.)   (156/345.43.45.)   (156/345.43.45.)   (156/345.43.45.)   (156/345.43.45.)   (156/345.43.45.)   (156/345.43.45.)   (156/345.44.156/345.45.)   (156/345.43.45.)   (156/345.43.45.)   (156/345.43.45.)   (156/345.44.156/345.45.156/345.46.)   USPAT   2004/01/13 11:30   (156/345.43.45.45.45.45.)   (156/345.43.156/345.44.156/345.45.156/345.46.)   USPAT   2004/01/13 11:30   (156/345.43.156/345.44.156/345.45.156/345.46.)   USPAT   2004/01/13 11:31   (156/345.43.156/345.44.156/345.45.156/345.46.)   USPAT   2004/01/13 11:31   (156/345.43.156/345.44.156/345.45.156/345.46.)   USPAT   2004/01/13 11:32   (156/345.43.156/345.44.156/345.45.156/345.46.)   USPAT   2004/01/13 11:33   (156/345.43.156/345.44.156/345.45.156/345.46.)   USPAT   2004/01/13 11:33   (156/345.43	_	538		LISPAT	2004/01/13 08:05
1978   (118/773e),CCLS.   156/345.43; 156/345.45; 156/345.46;   156/345.47; 156/345.43; 156/345.43; 156/345.45; 156/345.46;   156/345.47; 156/345.43; 156/345.45; 156/345.46;   156/345.47; 156/345.43; 156/345.45; 156/345.46;   156/345.47; 156/345.45; 156/345.46;   156/345.47; 156/345.47; 156/345.45; 156/345.46;   156/345.47; 156/345.46;   156/345.47; 156/345.44; 156/345.45; 156/345.46;   156/345.47; 156/345.44; 156/345.45; 156/345.46;   156/345.47; 156/345.44; 156/345.45; 156/345.46;   156/345.47; 156/345.44; 156/345.45; 156/345.46;   156/345.47; 156/		330		031711	200 1,01,13 00.03
1292   ((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CLS.)   ((156/345.47).CLS.)   ((156/345	_	978		USPAT	2004/01/13 08:07
48   (((156/345.43; 156/345.45; 156/345.46; 156/345.46; 156/345.47).CLS.)) not @pdc=20030601	-	1		USPAT	
156/345.47, CCLS.) (1.18/723e).CCLS.) in ot @pdc=20030601					
1 ("5702562") PN.   2004/01/13 10:00   10 ("6178919") or ("6129806") or ("6165376") or ("0594713") or ("5300460") or ("61717438") or ("5942075") or ("5772833") or ("579849") or ("510287") PN.   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:01   2004/01/13 10:02   2004/01	-	48		USPAT	2004/01/13 08:10
10   ("61/78919") or ("61/29806") or ("616/3576") or ("0594713") or ("5779849") or ("6110287") P.N.     219041   (wafer substrate work object) with (size diameter) and 118/723e.cds.     263   (wafer substrate work object) with (size diameter) and 118/723e.cds.     264   (wafer substrate work object) with (size diameter) and 118/723e.cds.     265   (file/723e.ods.     266   (wafer substrate work object) with (size diameter) and 118/723e.cds.     276   (file/723e.ods.     277   (file/723e.ods.     278   (fi				LICRAT	2004/04/42 00 40
("5300460") or ("6171438") or ("5942075") or ("5772833") or ("5779849") or ("6110287")) PN.  219041 (wafer substrate work object) with (size diameter)	_	1		1	
("5779494") or ("611028").PN. 219041 ("wafer substrate work object) with (size diameter) 118/723e.ccls. 263 ((wafer substrate work object) with (size diameter)) and 118/723e.ccls. 263 ((wafer substrate work object) with (size diameter)) and 118/723e.ccls. 264 ((wafer substrate work object) with (size diameter)) and 156/345.43.ccls. 265 ((wafer substrate work object) with (size diameter)) and 155/345.43.ccls. 266 ((wafer substrate work object) with (size diameter)) and 156/345.44.ccls. 276 (wafer substrate work object) with (size diameter) and 156/345.45.ccls. 287 (wafer substrate work object) with (size diameter) and 156/345.44.ccls. 388 (wafer substrate work object) with (size diameter) and 156/345.44.ccls. 399 (wafer substrate work object) with (size diameter) and 156/345.44.ccls. 390 (wafer substrate work object) with (size diameter) and 156/345.44.ccls. 391 (wafer substrate work object) with (size diameter) and 156/345.44.ccls. 391 (wafer substrate work object) with (size diameter) and 156/345.44.ccls. 390 (wafer substrate work object) with (size diameter) and 156/345.44.ccls. 391 (wafer substrate work object) with (size diameter) and 156/345.44.ccls. 392 (wafer substrate work object) with (size diameter) and 156/345.44.ccls. 393 (wafer substrate work object) with (size diameter) and 156/345.44.ccls. 394 (wafer substrate work object) with (size diameter) and 156/345.44.ccls. 395 (wafer substrate wafer) uspart 2004/01/13 11:29 2004/01/13 11:39 2004/01/13 11:	-	10		USFAI	2004/01/13 10.00
219041					
118/723e.ccls.   128/725   1204/01/13 10:02   128/725   1204/01/13 10:02   118/723   1204/01/13 10:02   12	-	219041		USPAT	
263 ((wafer substrate work object) with (size diameter)) and 118/723r.cds. ((wafer substrate work object) with (size diameter)) and 156/345.43.cds. ((wafer substrate work object) with (size diameter)) and 156/345.45.cds. (user substrate work object) with (size diameter)) and 156/345.45.cds. 38 ((wafer substrate work object) with (size diameter)) and 156/345.45.cds. 38 ((wafer substrate work object) with (size diameter)) and 156/345.45.cds. 39 ((wafer substrate work object) with (size diameter)) and 156/345.44.cds. (user substrate work object) with (size diameter)) and 156/345.44.cds. (user substrate work object) with (size diameter)) and 156/345.44.cds. (user substrate work object) with (size diameter)) and 156/345.47.cds. (user algorithm object) with (size diameter)) and 156/345.47.cds. (user) and 156/345.47.cds. (user	-	431		USPAT	2004/01/13 10:01
118/723r.cds.					
69 ((wafer substrate work object) with (size diameter)) and 156/345.43.cds. 69 ((wafer substrate work object) with (size diameter)) and 156/345.43.cds. 70 22 ((wafer substrate work object) with (size diameter)) and 156/345.45.cds. 80 ((wafer substrate work object) with (size diameter)) and 156/345.45.cds. 81 (wafer substrate work object) with (size diameter)) and 156/345.44.cds. 82 ((wafer substrate work object) with (size diameter)) and 156/345.44.cds. 83 ((wafer substrate work object) with (size diameter)) and 156/345.47.cds. 84 (usefer substrate work object) with (size diameter)) and 156/345.47.cds. 85 (usefer substrate work object) with (size diameter)) and 156/345.47.cds. 86 (algoe adj2 displays) and (large with (substrate wafer)) USPAT 2004/01/13 11:30 156/345.43; 156/345.44; 156/345.45; 156/345.46; USPAT 2004/01/13 11:31 156/345.43; 156/345.44; 156/345.45; 156/345.46; USPAT 2004/01/13 11:32 156/345.47).CCLS. 87 (118/723e).CCLS. 88 (156/345.43; 156/345.44; 156/345.45; 156/345.46; USPAT 2004/01/13 11:32 156/345.47).CCLS. 89 (156/345.43; 156/345.44; 156/345.45; 156/345.46; USPAT 2004/01/13 11:32 156/345.47).CCLS.) ((118/723e).CCLS.) USPAT 2004/01/13 11:32 156/345.47).CCLS.) ((118/723e).CCLS.) (118/723e).CCLS.) (USPAT 2004/01/13 11:33 156/345.47).CCLS.) ((118/723e).CCLS.) (118/723e).CCLS.) (USPAT 2004/01/13 11:33 156/345.47).CCLS.) ((118/723e).CCLS.) (118/723e).CCLS.) (USPAT 2004/01/13 11:33 156/345.47).CCLS.) ((118/723e).CCLS.) (	-	263		USPAT	2004/01/13 10:02
156/345.43.ccls.		67		LICDAT	2004/01/13 10:03
G9	Ī -	67	1 **	USFAT	2007/01/13 10:02
156/345.46.ccls.	_	69		USPAT	2004/01/13 10:02
156/345.45.ccls.			156/345.46.ccls.		
Section	-	22		USPAT	2004/01/13 10:02
156/345.44.cds.					
Section   Continue	-	38		USPAT	2004/01/13 10:02
156/345.47.ccls.   1076   1078   10	_	8Q		LICDAT	2004/01/13 11:20
- 7807   large adj2 display\$   USPAT   2004/01/13 11:30   USPAT   2004/01/13 11:31   USPAT   2004/01/13 11:32   USPAT   USPAT   2004/01/13 11:32   USPAT   USPAT   2004/01/13 11:32   USPAT   USPAT   2004/01/13 11:32   USPAT   2004/01/13 11:33   USPAT   2004/01/13 11:34   USPAT   2004/01/13 11:34   USPAT   2004/01/13 11:34   USPAT   2004/01/13 11:35   USP		09		OSFAI	2004/01/13 11.23
- 1076 (large adj2 display\$) and (large with (substrate wafer)) - 688 (156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS. US-PGPUB - 1166 (118/723e).CCLS. US-PGPUB - 538 (156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS. US-PGPUB USPAT;	-	7807		USPAT	2004/01/13 11:30
156/345.47).CCLS.	-	1076	(large adj2 display\$) and (large with (substrate wafer))	USPAT	
- 1166 (118/723e).CCLS. USPAT; US-PGPUB USPAT (118/723e).CCLS. 156/345.44; 156/345.45; 156/345.46; USPAT 2004/01/13 11:31 156/345.47).CCLS. USPAT 2004/01/13 11:32 17 1 ("000067").PN. USPAT 2004/01/13 11:32 17 150/345.43; 156/345.44; 156/345.45; 156/345.46; USPAT 2004/01/13 11:32 17 150/345.47).CCLS.) ((118/723e).CCLS.) (118/723e).CCLS.) ((156/345.43; 156/345.44; 156/345.45; 156/345.46; USPAT 2004/01/13 11:33 156/345.47).CCLS.) ((118/723e).CCLS.)) and (large adj2 display\$) (((156/345.43; 156/345.44; 156/345.45; 156/345.46; USPAT 2004/01/13 11:33 156/345.47).CCLS.) ((118/723e).CCLS.)) and ((large adj2 display\$) ((118/723\$,.ccls. 156/345\$,.ccls.) and (large adj2 display\$) (118/723\$,.ccls. 156/345\$,.ccls.) and (large adj2 display\$) (118/723\$,.ccls. 156/345\$,.ccls.) and (large adj2 (substrate wafer)) (118/723\$,.ccls. 156/745\$,.ccls.) (118/723\$,.ccls. 156/745\$,.ccls.	-	688			2004/01/13 11:31
- 538 (156/345.43; 156/345.44; 156/345.45; 156/345.46; USPAT 2004/01/13 11:31 156/345.47).CCLS 978 (118/723e).CCLS 1 ("0000067").PN. USPAT 2004/01/13 11:32 156/345.47).CCLS.) ((118/723e).CCLS.) - 1 (((156/345.43; 156/345.44; 156/345.45; 156/345.46; USPAT 2004/01/13 11:32 156/345.47).CCLS.) ((118/723e).CCLS.) - 1 (((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.) ((118/723e).CCLS.)) and (large adj2 display\$) - 1 (((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.) ((118/723e).CCLS.)) and (large adj2 display\$) - 1 (((156/345.47).CCLS.) ((118/723e).CCLS.)) and (large adj2 display\$) - 1 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 display\$) - 4746 118/723\$.ccls. 156/345\$.ccls.) and (large adj2 display\$) - 1512 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 display\$) - 1512 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc. and (large adj2 (substrate wafer)) - 755417 h01l021\$.ipc. c23c0156\$.ipc. and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))					2004/04/42 44 22
-   538   (156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.   USPAT   2004/01/13 11:31   156/345.47).CCLS.   USPAT   2004/01/13 11:32   2004/01/13 11:32   2004/01/13 11:32   2004/01/13 11:32   2004/01/13 11:32   2004/01/13 11:32   2004/01/13 11:32   2004/01/13 11:32   2004/01/13 11:32   2004/01/13 11:33   2004/01/13 1	-	1100	(118/723e).CCLS.		2004/01/13 11:32
156/345.47).CCLS.   USPAT   2004/01/13 11:32   1292   ((156/345.43; 156/345.44; 156/345.45; 156/345.46;	_	538	(156/345.43: 156/345.44: 156/345.45: 156/345.46:		2004/01/13 11:31
- 1 ("0000067").PN. ((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.) ((118/7239.CCLS.) ((118/7239.CCLS.) ((118/7239.CCLS.)) and (large adj2 display\$) (((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.) ((118/7239.CCLS.)) and (large adj2 display\$) (((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.) ((118/7239.CCLS.)) and ((large adj2 display\$) (((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.) ((118/7239.CCLS.)) and ((large adj2 display\$) (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 display\$) (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 display\$) (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) (USPAT 2004/01/13 11:38 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) (USPAT 2004/01/13 11:39 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) (USPAT 2004/01/13 11:39 (vafer))) and (cathode anode electrode) (large adj2 (substrate wafer)) (USPAT 2004/01/13 11:39 (vafer))) and (cathode anode electrode) (large adj2 (substrate wafer)) (USPAT 2004/01/13 12:07 (USPAT 2004/01/13 12:08 (USPAT 2004/01/13 12:03 (USPAT 2004/01/13 1					
- 1292 ((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.) ((118/723e).CCLS.) and (large adj2 display\$) - 1 (((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.) ((118/723e).CCLS.)) and (large adj2 display\$) - 1 (((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.) ((118/723e).CCLS.)) and ((large adj2 display\$) - 1 ((156/345.47).CCLS.) ((118/723e).CCLS.)) and ((large adj2 display\$) - 1 (18/723\$.ccls. 156/345\$.ccls.) and (large adj2 display\$) - 1 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 display\$) - 1 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) - 1 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) - 1 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) - 1 ((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) - 755417 h01l021\$.ipc. c23c0156\$.ipc. and (large adj2 (substrate wafer)) - 1 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))	-	978			
156/345.47).CCLS.) ((118/723e).CCLS.)   USPAT   2004/01/13 11:33   156/345.47).CCLS.) ((118/723e).CCLS.)) and (large adj2 display\$)   USPAT   2004/01/13 11:33   156/345.47).CCLS.) ((118/723e).CCLS.)) and (large adj2 display\$)   USPAT   2004/01/13 11:33   156/345.47).CCLS.) ((118/723e).CCLS.)) and ((large adj2 display\$)   USPAT   2004/01/13 11:33   156/345.47).CCLS.) ((118/723e).CCLS.)) and ((large adj2 display\$)   USPAT   2004/01/13 11:34   USPAT   2004/01/13 11:34   USPAT   2004/01/13 11:35   USPAT   2004/01/13 11:37   USPAT   2004/01/13 11:38   USPAT   2004/01/13 11:39   USPAT		_			
1 (((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.) ((118/723e).CCLS.)) and (large adj2 display\$) 1 (((156/345.47).CCLS.) ((118/723e).CCLS.)) and (large adj2 display\$) 1 (((156/345.47).CCLS.) ((118/723e).CCLS.)) and ((large adj2 display\$) 1 (156/345.47).CCLS.) ((118/723e).CCLS.)) and ((large adj2 display\$) 2 (display\$) and (large with (substrate wafer))) 3 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 display\$) 4 (118/723\$.ccls. 156/345\$.ccls.) and (large with (substrate wafer)) 4 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) 5 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) 4 ((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) 4 ((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) 5 (((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) 5 (((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) 5 (((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) 6 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 7 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 7 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 7 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))		1292		USPAT	2004/01/13 11:32
156/345.47).CCLS.) ((118/723e).CCLS.)) and (large adj2 display\$) (((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.) ((118/723e).CCLS.)) and ((large adj2 display\$) and (large with (substrate wafer)))  4746 118/723\$.ccls. 156/345\$.ccls. 10 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 display\$) (118/723\$.ccls. 156/345\$.ccls.) and (large with (substrate wafer))  1512 (118/723\$.ccls. 156/345\$.ccls.) and (large with (substrate wafer)) (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer))  445 ((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer))  575417 h01l021\$.ipc. c23c0156\$.ipc. and (large adj2 (substrate wafer))  6 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  755417 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  756417 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  1868 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  1869 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  190; 2004/01/13 12:07  DERWENT JPO; 2004/01/13 12:08  DERWENT JPO; 2004/01/13 12:08  DERWENT JPO; 2004/01/13 12:08	_	. 1		LICDAT	2004/01/13 11:22
1 (((156/345.43; 156/345.44; 156/345.45; 156/345.46; 156/345.47).CCLS.) ((118/723e).CCLS.)) and ((large adj2 display\$) and (large with (substrate wafer)))  4746 118/723\$,ccls. 156/345\$,ccls. USPAT 2004/01/13 11:34  10 (118/723\$,ccls. 156/345\$,ccls.) and (large adj2 display\$) USPAT 2004/01/13 11:37  1512 (118/723\$,ccls. 156/345\$,ccls.) and (large with (substrate wafer))  10 (118/723\$,ccls. 156/345\$,ccls.) and (large adj2 (substrate wafer))  11 (118/723\$,ccls. 156/345\$,ccls.) and (large adj2 (substrate wafer))  12 (118/723\$,ccls. 156/345\$,ccls.) and (large adj2 (substrate wafer))  13 ((118/723\$,ccls. 156/345\$,ccls.) and (large adj2 (substrate wafer))  14 (118/723\$,ccls. 156/345\$,ccls.) and (large adj2 (substrate wafer))  15 (118/723\$,ccls. 156/345\$,ccls.) and (large adj2 (substrate wafer))  16 ((118/723\$,ccls. 156/345\$,ccls.) and (large adj2 (substrate wafer))  17 ((118/723\$,ccls. 156/345\$,ccls.) and (large adj2 (substrate wafer))  18 ((118/723\$,ccls. 156/345\$,ccls.) and (large adj2 (substrate wafer))  18 ((118/723\$,ccls. 156/345\$,ccls.) and (large adj2 (substrate wafer))  19 (2004/01/13 12:07 DERWENT JPO; DERWENT JPO; DERWENT JPO; DERWENT JPO; DERWENT JPO; 2004/01/13 12:08 Wafer))) and (cathode anode electrode)) and (large adj2 (substrate wafer))  18 (((h01l021\$,ipc. c23c0156\$,ipc.) and (large adj2 (substrate wafer)) DERWENT JPO; 2004/01/13 12:08 DERWENT JPO; 2004/01/13 12:13	-	1		USFAI	2007/01/13 11.33
156/345.47).CCLS.) ((118/723e).CCLS.)) and ((large adj2 display\$) and (large with (substrate wafer)))   4746   118/723\$.ccls. 156/345\$.ccls.   USPAT   2004/01/13 11:34     10	_	1		USPAT	2004/01/13 11:33
display\$) and (large with (substrate wafer))    4746					, -,
- 10 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 display\$) USPAT 2004/01/13 11:37 1512 (118/723\$.ccls. 156/345\$.ccls.) and (large with (substrate wafer)) USPAT 2004/01/13 11:38 2004/01/13 11:38 2004/01/13 11:38 2004/01/13 11:38 2004/01/13 11:38 2004/01/13 11:38 2004/01/13 11:38 2004/01/13 11:39 2004/01/13 1			display\$) and (large with (substrate wafer)))		
- 1512 (118/723\$.ccls. 156/345\$.ccls.) and (large with (substrate wafer)) 574 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) 445 ((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) 445 (USPAT 2004/01/13 11:39 45 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) 46 (USPAT 2004/01/13 11:39 46 (DSPAT 2004/01/13 12:07 47 (DERWENT 2004/01/13 12:07 47 (NO11021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 47 (((NO11021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 48 ((NO11021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 49 ((NO11021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 40 ((NO11021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 40 ((NO11021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 40 ((NO11021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 41 (NO11021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 41 (NO11021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 41 (NO11021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) 42 (NO11/13 12:07	-	t .			
- 574 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) - 445 ((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) - 755417 (118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) - 755417 h01l021\$.ipc. c23c0156\$.ipc. and (large adj2 (substrate wafer)) - 755417 h01l021\$.ipc. c23c0156\$.ipc 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))	-				
- 445 ((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate wafer)) and (cathode anode electrode) - 755417 h01l021\$.ipc. c23c0156\$.ipc. and (large adj2 (substrate wafer)) - 755417 h01l021\$.ipc. c23c0156\$.ipc 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer)) - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))					
-       755417       wafer))) and (cathode anode electrode)       JPO;       2004/01/13 12:07         -       755417       h01l021\$.ipc. c23c0156\$.ipc.       JPO;       DERWENT         -       JPO;       DERWENT         JPO;       DERWENT         JPO;       DERWENT         JPO;       DERWENT         JPO;       DERWENT         JPO;       DERWENT         DERWENT       JPO;       2004/01/13 12:07         DERWENT       JPO;       2004/01/13 12:08         wafer))) and (cathode anode electrode)) and (large adj2 (substrate wafer))       DERWENT         JPO;       DERWENT         JPO;       2004/01/13 12:08         DERWENT       JPO;       2004/01/13 12:13	-				
- 755417 h01l021\$.ipc. c23c0156\$.ipc. and (large adj2 (substrate wafer))  - 755417 h01l021\$.ipc. c23c0156\$.ipc.  - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  - 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))				- <b></b>	==0.,0=,20.12.00
- 755417 h01l021\$.ipc. c23c0156\$.ipc. DERWENT JPO; DERWENT DERWENT JPO; DERWENT JPO	-	755417			2004/01/13 12:07
- 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  - 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))  - 312 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate yafer))  - 312 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate yafer))  - 312 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate yafer))  - 312 (2004/01/13 12:13					
- 1867 (h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))	-	755417	h01l021\$.ipc. c23c0156\$.ipc.		2004/01/13 12:07
DERWENT  O (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))) and (cathode anode electrode)) and (large adj2 display\$)  OERWENT  DERWENT		1007	(h01 0214 inc. a22a01564 inc.) and (laws a dift (a) between the conference		2004/01/12 12:07
- 0 (((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))) and (cathode anode electrode)) and (large adj2 display\$) DERWENT ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate JPO; 2004/01/13 12:13	-	186/	(notiozta.ipc. czacotooa.ipc.) and (large adjz (substrate water))	•	2004/01/13 12:0/
wafer))) and (cathode anode electrode)) and (large adj2 display\$) DERWENT ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate JPO; 2004/01/13 12:13	_	0	(((h01 021\$.ipc, c23c0156\$.ipc.) and (large adi2 (substrate		2004/01/13 12:08
- 312 ((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate JPO; 2004/01/13 12:13					_00.,01,10.12.00
wafer))) and (cathode anode electrode)  DERWENT	_	312	((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate	JPO;	2004/01/13 12:13
		<u> </u>	wafer))) and (cathode anode electrode)	DERWENT	

_	5	(((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate	JPO	2004/01/13 13:05
		wafer))) and (cathode anode electrode)) and (meter\$ inch\$2)		2004/04/42 42 45
-	54	(((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate	JPO	2004/01/13 12:16
İ		wafer))) and (cathode anode electrode)) and (m in)		
-	544	((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate	USPAT	2004/01/13 12:23
		wafer))) and ((wafer substrate) with ("m" "in"))	1	
_	348	((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate	USPAT	2004/01/13 12:31
		wafer))) and ((wafer substrate) near4 ("m" "in"))		
-	74	((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate	USPAT	2004/01/13 12:24
		wafer))) and ((wafer substrate) near ("m" "in"))		
-	19	((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate	JPO	2004/01/13 12:33
		wafer))) and (meter\$ inch\$2)		
-	14	(((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate	JPO	2004/01/13 12:36
1		wafer))) and (meter\$ inch\$2)) not ((((h01l021\$.ipc.		
		c23c0156\$.ipc.) and (large adj2 (substrate wafer))) and (cathode	1	
		anode electrode)) and (meter\$ inch\$2))		2001/01/10 10 77
-	2829	"applied materials".as.	USPAT	2004/01/13 12:37
-	1	"applied materials".as. and (large adj2 display\$)	USPAT	2004/01/13 12:39
-	255	"applied materials".as. and (large adj2 (substrate\$ wafer\$))	USPAT	2004/01/13 12:59
-	2	("applied materials".as. and (large adj2 (substrate\$ wafer\$))) and	USPAT	2004/01/13 13:05
		("m.sup.2" "in.sup.2")		2004/01/12 12:01
-	26		USPAT	2004/01/13 13:01
		"5092729"   "5179498"   "5304249"   "5310453"   "5366585"		
		"5399387"   "5413360"   "5458687"   "5531835"   "5547539"		
		"5558717"   "5790365"   "5874361"   "5897711"   "5900062"		
		"5904779"   "5906684"   "5910338"   "6001432"   "6028762"		
		"6177023").PN.	LICDAT	2004/01/13 13:04
-	18	("4184188"   "4298443"   "4384918"   "4431473"   "4931135"	USPAT	2004/01/13 13.04
		"5092729"   "5179498"   "5304249"   "5310453"   "5458687"		
		"5547539"   "5790365"   "5897711"   "5900062"   "5904779"	1	
		"5906684"   "5910338"   "6001432").PN.	JPO;	2004/01/13 13:06
- :	0	(((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate	DERWENT	2004/01/13 13:00
		wafer))) and (cathode anode electrode)) and ("m.sup.2"	DERVILINI	
	۾ ا	"in.sup.2")  ((h0.110.214 in a 2.22.01.E64 in a ) and (large adi2 (substrate	JPO;	2004/01/13 13:06
-	0	((h01l021\$.ipc. c23c0156\$.ipc.) and (large adj2 (substrate wafer))) and ("m.sup.2" "in.sup.2")	DERWENT	200 1,01,13 13.00
	Ó	(h01l021\$.ipc. c23c0156\$.ipc.) and ("m.sup.2" "in.sup.2")	JPO;	2004/01/13 13:06
_		(Hothostaliher espectatoaliher) and (Hisahis Hisahis)	DERWENT	250 1, 52, 15 15.00
1_	21	(((118/723\$.ccls. 156/345\$.ccls.) and (large adj2 (substrate	USPAT	2004/01/13 13:15
	21	wafer))) and ((wafer substrate) with ("m" "in"))) and ("m.sup.2"		
		"in.sup.2")		
_	1	("5981899").PN.	DERWENT	2004/01/13 13:18
_	1	1998-414355.NRAN.	DERWENT	2004/01/13 13:16
	1	("6177023").PN.	DERWENT	2004/01/13 13:20
:	1	1999-250789.NRAN.	DERWENT	2004/01/13 13:18
_	1	("6298685").PN.	DERWENT	2004/01/13 13:21
_	1	2001-612327.NRAN.	DERWENT	2004/01/13 13:20
-	2	(("5942075") or ("6178919")).PN.	DERWENT	2004/01/13 13:23
-	1	2000-611214.NRAN.	DERWENT	2004/01/13 13:21
-	1	1997-223617.NRAN.	DERWENT	2004/01/13 13:22
_	3	(("5942075") or ("6178919") or ("5237152")).PN.	USPAT	2004/01/13 14:47
-	2	(("5272417") or ("5210466")).PN.	USPAT	2004/01/13 14:52
-	1	("6177023").PN.	USPAT	2004/01/13 14:52